

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/12/2022

Details for "TPS7A7200RGWT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TPS7A7200RGWT	NIPDAU	Level-2-260C-1 YEAR	TI PHILIPPINES CLARK A/T	RGW   20	5x5x0.9	82

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.370465	99.99946	999995	0.451718	4517
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.00027	3	0.000001	0
Precious Metals	Silver	7440-22-4	0.000001	0.00027	3	0.000001	0
Sub-Total			<b>0.370467</b>	<b>100</b>	<b>1000000</b>	<b>0.451721</b>	<b>4517</b>
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.33385	80.000096	800001	0.407073	4071
Thermoplastics	Epoxy	85954-11-6	0.083462	19.999904	199999	0.101768	1018
Sub-Total			<b>0.417312</b>	<b>100</b>	<b>1000000</b>	<b>0.50884</b>	<b>5088</b>
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	43.884	97.52	975200	53.508974	535090
Copper and Its Alloys	Iron	7439-89-6	1.035	2.3	23000	1.262004	12620
Copper and Its Alloys	Phosphorus	7723-14-0	0.0135	0.03	300	0.016461	165
Zinc and Its Alloys	Zinc	7440-66-6	0.0675	0.15	1500	0.082305	823
Sub-Total			<b>45</b>	<b>100</b>	<b>1000000</b>	<b>54.869743</b>	<b>548697</b>
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	1.33168	95.12	951200	1.623754	16238
Precious Metals	Gold	7440-57-5	0.01092	0.78	7800	0.013315	133
Precious Metals	Palladium	7440-05-3	0.0574	4.1	41000	0.069989	700
Sub-Total			<b>1.4</b>	<b>100</b>	<b>1000000</b>	<b>1.707059</b>	<b>17071</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	29.503866	88.000001	880000	35.974879	359749
Other Organic Materials	Chlorine	7782-50-5	0.000335	0.000999	10	0.000408	4
Other Plastics and Rubber	Carbon Black	1333-86-4	0.100581	0.299999	3000	0.122641	1226
Thermoplastics	Epoxy	85954-11-6	3.922338	11.699001	116990	4.782615	47826
Sub-Total			<b>33.52712</b>	<b>100</b>	<b>1000000</b>	<b>40.880544</b>	<b>408805</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	1.297513	100	1000000	1.582093	15821
Sub-Total			<b>1.297513</b>	<b>100</b>	<b>1000000</b>	<b>1.582093</b>	<b>15821</b>
<b>Total</b>			<b>82.012412</b>			<b>100</b>	<b>1000000</b>

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/eoinfo](http://www.ti.com/eoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.